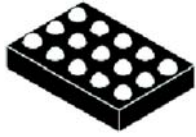


# MECHANICAL CASE OUTLINE

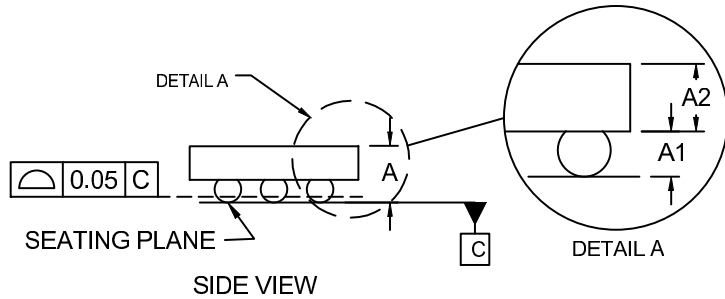
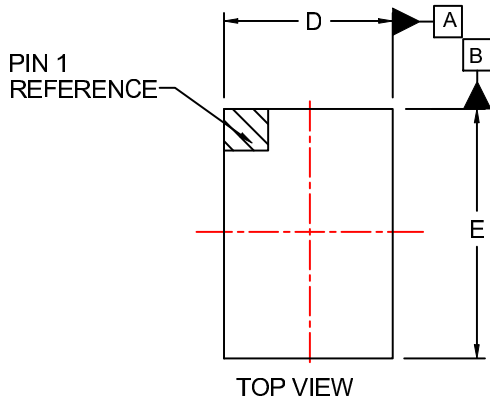
## PACKAGE DIMENSIONS

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**WLCSP15, 1.49x2.06x0.574**  
 CASE 567WV  
 ISSUE O

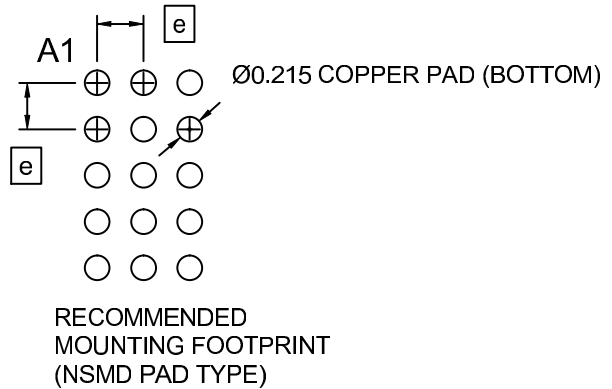
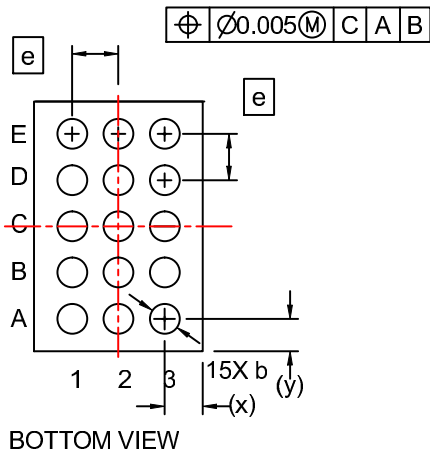
DATE 12 JUL 2018



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.178	0.196	0.214
A2	0.358	0.378	0.398
b	0.240	0.260	0.280
D	1.460	1.490	1.520
E	2.030	2.060	2.090
e	0.40 BSC		
x	0.330	0.345	0.360
y	0.215	0.230	0.245



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